

Embedded E-MARK, fanless embedded computer,
EN50155 certification with 4x RJ45 PoE + ports, DIO,
CAN bus and RAID GEN 8/9

FEATURES

- Supports Intel® 8th / 9th-Gen Core™ i7 / i5 / i3 LGA1151 socket-type CPU
- 4x 802.3at Gigabit PoE + ports via RJ45 connectors
- Isolated CAN bus for vehicle communication
- 4-CH isolated DI and 4-CH isolated DO
- 2x SATA ports with a hot-swappable HDD tray
- supports RAID 0/1
- 2x M.2
- 3x mini full size PCIe
- EN 50155 certificate and E-mark
- 8 ~ 35V broadband DC input, ignition control



SPECIFICATIONS

CPU	:	Supporting Intel® 8th/ 9th-Gen CPU (LGA1151 socket, 65W/ 35W TDP) - Intel® Core™ i7-8700/ i7-8700T/ i7-9700E/ i7-9700TE - Intel® Core™ i5-8500/ i5-8500T/ i5-9500E/ i5-9500TE - Intel® Core™ i3-8100/ i3-8100T/ i3-9100E/ i3-9100TE
Storage	:	1x hot-swappable tray for 2.5" SSD, 1x Internal SATA port for 2.5" SSD installation, supporting RAID 0/ 1 mSATA, 1x full-size mSATA port (mux with mini-PCIe) M.2, 1x M.2 2280 M key socket (PCIe Gen3 x4) for NVMe SSD or Intel® Optane™ memory installation
Chipset	:	Intel® Q370 Platform Controller Hub
Digital I/O	:	4x isolated DI and 4x isolated DO
USB	:	4x USB 3.1 Gen2 (10 Gbps) ports 4x USB 3.1 Gen1 (5 Gbps) ports
Operating Temp.	:	-40°C ~ 70°C For sub-zero operating temperature, a wide temperature HDD/SSD is required, For i7-8700 running at 65W mode, the highest operating temperature shall be limited to 50°C
Chok/Vibration	:	Operating, MIL-STD-810G, Method 514.6, Category 4 Shock Operating, MIL-STD-810G, Method 516.6, Procedure I, Table 516.6-II
Forsyning	:	1x 3-pin pluggable terminal block for 8~35V DC input (IGN/ GND/ V+) Remote Ctrl. & Status Output 1x 3-pin pluggable terminal block for remote control and PWR LED output
Grafik	:	Integrated Intel® HD Graphics 630, 1x VGA connector, supporting 1920 x 1200 resolution 1x DVI-D connector, supporting 1920 x 1200 resolution 1x DisplayPort connector, supporting 4096 x 2304 resolution
Hukommelse	:	Up to 64 GB DDR4 2666/ 2400 SDRAM (two SODIMM slots)
Interface	:	1x isolated CAN 2.0 port
Luftfugtighed	:	10%~90% , non-condensing



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M.2	:	2x M.2 2242 B key socket, one with dual front-accessible SIM sockets, supporting dual SIM mode with selected M.2 LTE module
Montering	:	patented damping bracket (standard) or optional DIN-rail mounting
mPCIe	:	1x full-size mini PCI Express socket with internal SIM socket (mux with mSATA) 2x full-size mini-PCIe sockets (USB signals only) with internal SIM sockets
Porte	:	2x software-programmable RS-232/422/485 ports (COM1/ COM2) 2x RS-232 ports (COM3/ COM4)
Udgange	:	1x VGA, supporting 1920 x 1200, 1x DVI-D connector 1920 x 1200 resolution 1x DisplayPort connector 4096 x 2304 resolution
Weight	:	3.3 Kg
Dimensioner	:	240 mm (W) x 225 mm (D) x 84 mm (H)

